1 2	3 4	5		6	7	8	
	- Paus /	RECOMM	MENDATION FOR	SOLDER PROCESS	SING		
harting har-flex straight male connector RoHS compliant			Solder paste recommendation				
			The har-flex connectors are solderable with established lead-free SAC / SnNi solder but also leaded solder e.g. SnPb40				
GENERAL INFORMATIONS							
No. of contacts from 6 to 100poles, all even numbers			PCB pad plating The har-flex connectors are solderable on lead-free pad surfaces like HAL, NiAu, Immersion Sn.				
No. of contacts from 6 to 100poles, all even numbers 1,27mm x 1,27mm [0,050"x0,050"]			The har-liex connectors are solderable on lead-free pad surfaces like HAL, NIAu, Immersion Sn.				
Test Voltage	500V	Stencil re	Stencil recommendation				
Contact resistance	< 25 mOhm	The solo	The solder deposition has to be placed on the pad area of the contact solder tines.				
Insulation resistance	≥ 10x10^9Ω		Ideally, the solder deposition has the same length-to-width ratio and center point like the PCB pads. The size of the solder stencil apertures is depending on the thickness of the stencil. In general, the thinner stencils will need larger apertures to result in the required volume of solder paste. The minimum required solder paste volume for the signal pins is 0,094mm³, for the hold down it is 0,33mm³. For example, this can be achieved with the following stencil data: Signal pins				
Working current acc. to IEC 60512, at 70°C, 80% derating	see derating diagram						
Working temperature range	-55°C +125°C	The min					
Termination technology	SMT						
6,	min. 150s >217°C						
Reflow processing temperature (acc. to ECA/IPC/JEDEC J-STD-075 Level PSL R0)	min. 30s>240°C		Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume	
Clearance & creepage distance	0.4mm min.	—— F	120 µm	1,1 x 0,8 mm	1,05 x 0,75 mm	0,095 mm ³	
Insertion force (depending on mating connector)	approximately 0,5N/contact	- 	150 µm	1,1 x 0,8 mm	0,99 x 0,72 mm	0,107 mm ³	
Withdrawal force (depending on mating connector)	approximately 0,5N/contact		100 μπ	1,1 % 0,0 111111	, ,	5,107 11111	
	PL1 : 500 mating cycles			DOD : :	Hold-downs		
Mating cycles	PL2 : 250 mating cycles		Stencil thickness	PCB pad size	proposal stencil aperture size	calculated solder paste volume	
RoHS - compliant	Yes		120 µm	2,5 x 1,2 mm	2,45 x 1,15 mm	0,338 mm³	
Leadfree	Yes		150 µm	2,5 x 1,2 mm	2,25 x 1,08 mm	0,365 mm³	
Working voltage acc. to to IEC 60664-1	100V / 150V (depending on installation category)		If a stencil with lower thickness shall be used, please insure the minimum required solder paste volume by enlarging the				
UL file acc. UL 1977	ECBT2.E102079		stencil aperture. Depending on the PCB design, the solder depostion may protrude the PCB pads. But to achieve a good sealing during solder paste printing and to reduce the cleaning interval of the stencil, the aperture should be smaller than the PCB pad about 10% or 25µm encircling.				
UL file acc. CSA-C22.2 (for Canada)	ECBT8.E102079						
PSL level acc. ECA/IPC/JEDEC J-STD-075	PSL R0	I					
MSL level acc. ECA/IPC/JEDEC J-STD-020D	MSL 1			Coplanarity of contacts All connectors are tested for coplanarity of contacts and are in the range of 6 pin to 80 pin: ≤ 0.1mm			
INSULATOR MATERIAL			All connectors are tested for copianarity of contacts and are in the range of 6 pin to 80 pin: ≤ 0.15mm 82 pin to 100 pin: ≤ 0.15mm				
			Performance level 82 pin to 100 pin: ≤ 0.15mm				
Material	LCP (liquid crystalline polymer)	<u> </u>			• H (I)		
Color	Black		Performance level 1 (recommended for majority of applications) Initial 250 mating cycles, 10 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb. Measurement of contact resistance. The remaining 250 mating cycles are subject to measurement of contact resistance and visual inspection.				
UL classification	UL94-V0						
Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)	and visual					
CONTACT MATERIAL	Visual insp	Visual inspection. No abrasion of the contact finish through to the base material. No functional impairment. Part number definition: 15 2					
Contact material	Conner allow	ran numb	er denimbon: 15 .	4			
Plating termination zone	Copper alloy Sn		Performance level 2 Initial 125 mating cycles, 4 days gas test (25°C / 75% r.h.) using H2S 10 ppb, NO2 200 ppb, CL2 10 ppb, SO2 200 ppb. Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance.				
Plating contact sliding side	Au over PdNi (acc. to Performance level)						
	AU OVEL I UIVI (AUG. IO FEITOTTIATICE IEVEI)	rmance level) Measurement of contact resistance. The remaining 125 mating cycles are subject to measurement of contact resistance and visual inspection.					
DERATING DIAGRAM acc. to IEC 60512-5 (Current carrying capacity)		Visual insp	ection. No abrasio		sh through to the base material. No	o functional impairment.	
The current carrying capacity is limited by maximum temperature of materials for inserts and contacts including terminals.	A Further East - Stilland	Part numb Performan Defined co	Part number definition: 15 6 Performance level S4 Defined contact surface of min. 0,06 µm Au over 0,7+0,2µm PdNi Part number definition: 15 5 All Dimensions in mm Original Size DIN A3 All rights reserved Created by Inspected by Standardisation Date State				
The current capacity curve is valid for continuous, non interrupted current loaded contacts of connectors when simultaneous power on all contacts is given, without exceeding the maximum temperature.	Electrical load [A]						
Control and test procedures according to DIN IEC 60512-5 derating curve at Imax*0,8 (IEC 60512-5-2)	0 10 20 30 40 50 60 70 80 90 100 110 120 130	UARTING	artment EC PD - CN	—— ZHUANGJ	LUOK HOFFMANN Hale THR stacking height1.75 and	2016-06-20 Final Release	
- ' ' '	Temperature [°C]	HARTING ELECT	ו טווונס שוווטוו	I I			
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